

CURRICULUM VITAE

University of Idaho

NAME: Timothy Murphy

DATE: January 2024

RANK OR TITLE: Assistant Professor of Law

DEPARTMENT: College of Law

OFFICE LOCATION AND CAMPUS ZIP:

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WEB:

DATE OF FIRST EMPLOYMENT AT UI: July 1, 2018

DATE OF TENURE: Untenured

DATE OF PRESENT RANK OR TITLE: August 15, 2021

EDUCATION BEYOND HIGH SCHOOL:

Degrees:

- J.D., University of Michigan Law School, Ann Arbor, Michigan, May 1, 2008, Law
- M.S.E.E., University of Michigan, Ann Arbor, Michigan, April 30, 2004, Electrical engineering/optoelectronics
- B.S.E.E., Boise State University, Boise, Idaho, May 12, 2002, Electrical engineering

Certificates and Licenses:

- Attorney, Idaho State Bar
- Patent Attorney, U.S. Patent and Trademark Office

EXPERIENCE:

Teaching, Extension and Research Appointments:

- Assistant Professor of Law, University of Idaho College of Law, 2021 to Present
- Assistant Clinical Professor of Law, University of Michigan Law School, July 2020 to May 2021
- Temporary Faculty and Director of the Entrepreneurship Law Clinic, University of Idaho College of Law, August 2018 to May 2020

Academic Administrative Appointments:

- None

Non-Academic Employment including Armed Forces:

- Sr. Patent and Trademark Counsel, Micron Technology, Inc., Boise, Idaho, August 2010-August 2018
- Associate Attorney, Zarian Midgley & Johnson, Boise, Idaho, January 2010-August 2010
- Associate Attorney, Marger Johnson & McCollum, Portland, Oregon, May 2007-December 2009
- Manufacturing Engineer, Micron Technology, Inc., Boise, Idaho, July 1995-May 2002
- Powerplant Operator, Idaho Power, Hagerman, Idaho, August 1994-July 1995
- Machinist's Mate, U.S. Navy, Norfolk, Virginia, June 1988-June 1994

Consulting:

- None

TEACHING ACCOMPLISHMENTS:

Areas of Specialization: Contracts, Intellectual Property, Jurisprudence

Courses Taught:

- Contracts LAW 8130, Fall `23
- Contracts I, LAW 813, Fall `21 and `22
- Contracts II, LAW 814, Spring `22 and `23
- Introduction to Intellectual Property, LAW 9030, Fall `21, `22, and `23
- Patents, LAW 931, Spring `19
- Patent Drafting, LAW 991, Spring `19
- Lawyering Process: Transactions, LAW 991, Fall `19
- Entrepreneurship Law Clinic, LAW 978, Fall `18 and `19 and Spring `19 and `20
- Internet Law, LAW 918, Spring `20

Students Advised:

Undergraduate Students:

- N/A

Graduate Students:

Advised to completion of degree-major professor – N/A
Served on graduate committee – N/A

Materials Developed:**Courses Developed:**

- Patent Drafting, LAW 991
- Lawyering Process: Transactions, LAW 991

Non-credit Classes, Workshops, Seminars, Invited Lectures, etc.:

- Jurisprudence Reading Group (Spring 2023)

Honors and Awards:

- 2023 Alumni Award for Excellence Inspirational Mentor

SCHOLARSHIP ACCOMPLISHMENTS:**Publications, Exhibitions, Performances, Recitals:****Refereed/Adjudicated:**

- Timothy Murphy, Can't Get It out of My Head: Trade Secrets Liability for Remembered Information, 2023 WIS. L. REV. 1929 (2023).
- Timothy Murphy, Memorizing Trade Secrets, 57 RICH. L. REV. 533 (2023).
- Timothy Murphy, How Can a Departing Employee Misappropriate Their Own Creative Outputs?, 66 VILL. L. REV. 529 (2021).
- Timothy Murphy, An Instance of Open Hardware: A Different Approach to Free and Open Source Hardware Licensing, 30 FORDHAM INTELL. PROP. MEDIA & ENT. L. J. 1045 (2020).
- Timothy E. Murphy, University of Idaho's Entrepreneurship Law Clinic: Providing Free Legal Services for Idaho Ventures, THE ADVOCATE, Vol. 62, No. 3/4, at p. 34.

Peer Reviewed/Evaluated:

- T.E. Murphy, D.Y. Chen, E. Cagin, and J.D. Phillips, Electronic Properties Of ZnO Epilayers Grown On C-Plane Sapphire By Plasma-Assisted Molecular Beam Epitaxy, Proceedings from the 22nd North American Molecular Beam Epitaxy Conference, October 10-13, 2004, Banff, Canada, Journal of Vacuum Science and Technology B, Volume 23 (3), 1277-1280 (2005).

- T.E. Murphy, D.Y. Chen, and J.D. Phillips, Growth And Electronic Properties Of ZnO Epilayers By Plasma-Assisted Molecular Beam Epitaxy, Proceedings from the 2004 U.S. Workshop on the Physics and Chemistry of II-VI Materials, October 5-7, 2004, Chicago, Illinois, Journal of Electronic Materials, Volume 34 (6), 699-703 (2005).
- T. E. Murphy, J. O. Blaszczyk, K. Moazzami, W. E. Bowen, And J. D. Phillips, Properties Of Electrical Contacts On Bulk And Epitaxial n-Type ZnO, Proceedings from the 46th TMS Electronic Materials Conference, June 23-25, 2004, Notre Dame, Indiana, Journal of Electronic Materials, Volume 34 (4), 389-394 (2005).
- T.E. Murphy, S. Walavalkar, and J.D. Phillips, Epitaxial growth and surface modeling of ZnO on c-plane Al₂O₃, Applied Physics Letters, Volume 85 (26), 6338-6340 (2004).
- T.E. Murphy, D.Y. Chen, and J.D. Phillips, Electronic Properties Of Ferroelectric BaTiO₃/MgO Capacitors On GaAs, Applied Physics Letters, Volume 85 (15), 3208-3210 (2004).
- D. Chen, T. E. Murphy, S. Chakrabarti, and J. D. Phillips, Optical Waveguiding In BaTiO₃/MgO/AlxOy/GaAs Heterostructures, Applied Physics Letters, Volume 85 (22), 5206-5208 (2004).
- D.Y. Chen, T.E. Murphy, and J.D. Phillips, Deposition Of BaTiO₃ Thin Films And MgO Buffer Layers On Patterned GaAs Substrates for Integrated Optics Applications, Materials Research Society 2003 Fall Meeting Proceedings, Volume 784, C11.23 (2004).
- T.E. Murphy, D.Y. Chen, and J.D. Phillips, Integration of BaTiO₃ Ferroelectric Thin Films with GaAs for Functional Devices, Proceedings of the 15th Biennial University/Government/Industry Microelectronics Symposium, June 30-July 2, 2003, Boise, Idaho (2003).

Other:

Refereed/Adjudicated (currently scheduled or submitted):

- Timothy Murphy, Do Androids Dream of Economic Incentives?, forthcoming Akron L. Rev. ____ (2024).

Peer Reviewed/Evaluated (currently scheduled or submitted):

Presentations and Other Creative Activities:

Professional Meeting Papers, Workshops, Showings, Recitals:

- Trade Secrets Issues for AI-generated Information, University of Akron School of Law IP Scholar's Forum, December 8, 2023.
- Trade Secret Protection for Routine Business Information, Intellectual Property Scholars Conference, August 3-4, 2023.
- Trade Secret Protection for Routine Business Information, 2023 Junior IP Scholars Association Workshop, August 1-2, 2023.
- Taxonomy of Remembered Trade Secret Information, 2023 Trade Secret Workshop, January 13, 2023
- Introducing Skills Exercises in First-Year Contracts, Faculty Teaching Retreat, March 25, 2022
- Employee Trade Secret Issues, 2022 Trade Secret Workshop, June 10-11, 2022
- Memorizing Trade Secrets, WIPIP 2022, Feb. 18-19, 2022
- Trade Secrets Liability for Remembered Information, Junior IP Scholars Association Workshop, July 22-23, 2021
- Remote Teaching Approaches for Inclusivity in Transactional Clinic Seminars, Northwest Clinical Law Conference, Nov. 5-7, 2020.

Patents: (provide title/description, patent number and date)

- US Patent Number 7,732,882, Method and system for electrically coupling a chip to chip package, issued June 8, 2010.
- US Patent Number 7,489,875, System and method for multiple bit optical data transmission in memory systems, issued February 10, 2009.
- US Patent Number 7,355,273, Semiconductor dice having back side redistribution layer accessed using through-silicon vias, methods, issued April 8, 2008.
- US Patent Number 7,335,985, Method and system for electrically coupling a chip to chip package, issued February 26, 2008.

- US Patent Number 7,254,331, System and method for multiple bit optical data transmission in memory systems, issued August 7, 2007.
- US Patent Number 7,015,559, Method and system for electrically coupling a chip to chip package, issued March 21, 2006.
- US Patent Number 6,936,489, Method and system for electrically coupling a chip to chip package, issued August 30, 2005.
- US Patent Number 6,914,317, Thin microelectronic substrates and methods of manufacture, issued July 5, 2005.
- US Patent Number 6,831,301, Method and system for electrically coupling a chip to chip package, issued December 14, 2004.
- US Patent Number 6,800,930, Semiconductor dice having back side redistribution layer accessed using through-silicon vias, and assemblies, issued October 5, 2004.
- US Patent Number 6,693,342, Thin microelectronic substrates and methods of manufacture, divisional from 6,303,469, issued February 17, 2004.
- US Patent Number 6,303,469, Thin microelectronic substrates and methods of manufacture, issued October 16, 2001.

Grants and Contracts Awarded:

Honors and Awards:

SERVICE:

Major Committee Assignments:

- U of I Faculty Senate, Senator for SW Idaho Region, Fall 2022 to present
- University Assessment and Accreditation Committee, member, Fall 2021 to present
- University Safety and Loss-Control Committee, member, Fall 2022 to present
- College of Law Curriculum Committee, chair, AY23-24
- College of Law DEI Committee, member, AY23-24
- College of Law Dean's Advisory Committee, member, AY23-24
- College of Law Dean Search Advisory Committee, member, AY23-24
- College of Law Academic Hearing Board, chair, AY22-23
- College of Law Curriculum Committee, member, AY22-23
 - UDWR Subcommittee, member, Fall 2022
 - First-Year Curriculum Subcommittee, AY22-23
- Search Committee for new University Ombuds (Summer 2022)
- College of Law Technology Committee, member, AY 2021-22
- Michigan Patent Pro Bono Program Review Committee (2020-2021)
- Idaho Volunteer Lawyers Program, Policy Council member (2010-2020)
- Idaho Technology Council Tech2Market Committee, member (2018-2020)
- Idaho Military Legal Alliance, board member (2018-2020)
- AALS Clinical Section, Membership, Outreach, and Training Committee, member (2019-2020)

Professional and Scholarly Organizations

- Idaho Military Legal Alliance, Steering Committee member and Treasurer, (2023 – present)
- Intellectual Property Section of the Idaho State Bar, Treasurer (2021-23), past Vice-Chair, Secretary, and member (2010-2020)
- Business and Corporate Law Section of the Idaho State Bar, member (2018-2019)
- Child Protection Section of the Idaho State Bar, member (2018-2019)

Outreach Service:

- AALS Conference on Clinical Legal Education, working group facilitator (May 2019)
- Northwest Clinical Law Conference, Planning Committee member (May-Nov. 2019)

Community Service:

- Pro Bono Legal Work

- Guardian ad litem representations in child protection cases (2014-2019)
- Hague Convention child abduction case (2016-2017)
- Divorce/custody cases (2009-2016)
- Small business dispute for refugee family (2014)
- § 1983 prisoner civil rights claim (2009-2010)

Honors and Awards:

- Denise O-Donnell-Day Pro Bono Award (2011)

PROFESSIONAL DEVELOPMENT:

Teaching:

- AALS Annual Conference, January 2023
- AALS Conference on Clinical Legal Education, May 2019
- Northwest Clinical Law Conference, November 2018, 2019, and 2020

Scholarship:

- University of Akron School of Law IP Scholar's Forum, December 2023.
- Intellectual Property Scholars Conference, August 2023.
- 2023 Junior IP Scholars Association Workshop, August 2023
- WIPIP 2023, February 2023
- Trade Secrets Workshop, January 2023
- Eighth Annual IP Mosaic Conference, October 2022
- Trade Secrets Workshop, June 2022
- WIPIP 2022, February 2022
- Junior IP Scholars Association Workshop, July 2021

Outreach:

Administration/Management: